

FEATURES

- 29 mΩ High-Side MOSFET
- 1.0~4.0 A (typ.) Adjustable Current Limit
- Low Average Current in OUT shorted GND
- Support Apple® Devices fast charging (Apple® 2.1A / 2.4A mode)
- Support Samsung Galaxy Tab Devices fast Charging
- Support BC1.2 & YD/T 1591-2009 Charging Spec
- Built-in Soft-Start
- Support single layer PCB layout.
- 2.7 ~ 6.5V Single Supply Operation.
- Available EMSOP8 package.

APPLICATIONS

- USB Charger
- USB Wall Adapter
- Car Charger

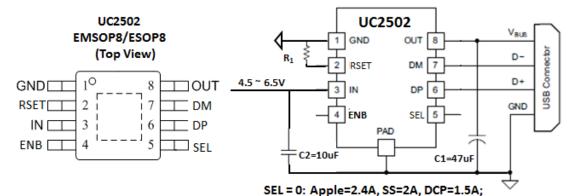
DESCRIPTION

The UC2502 integrated USB charger emulators with automatic host charger identification circuitry and high performance adjustable current limiting power switch. An automatic USB charger identification circuit allows mobile power supply can automatically provides the correct modes on the data lines to charger compliant devices among the Apple, Samsung and BC1.2 modes.

The UC2502 is a $29m\Omega$ power switch intended for applications where heavy capacitive loads and short-circuits are likely to be encountered. This also provides hiccup mode when OUT voltage is less than 3.0V or OTSD.

The UC2502 provides an ENB pin to turn on or turn off UC2502 and an SEL pin to select 10W or 12W mode in application.

PACKAGE AND APPLICATION



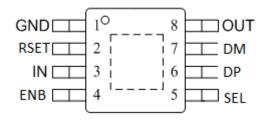
SEL = 1 or Floating: Apple=2.1A, SS=2A, DCP=1.5A; ENB is floating or pull down with 10k Resistor if not used

ORDING INFORMATION

Part Number	Package Type	Package Qty	Op Temp(°C)	Mark
UC2502	EMSOP8	3000	-40~85	UC2502

PINOUT

UC2502 EMSOP8/ESOP8 (Top View)



PIN FUNCTIONS

NO.	NAME	TYPE ⁽¹⁾	DESCRIPTION
1	GND	G	Ground connection
2	RSET	ı	External resistor used to set current-limit threshold;
3	IN	P/I	Power supply/Input voltage connected to Power Switch; connect a 1 µF or greater ceramic capacitor from IN to GND as close to the IC as possible
4	ENB	I	Enable input, logic low turns on UC2502
5	SEL	I	Logic-level control input; When it is high or floating, DP/DM operate in 2.1A mode, when it is Low, DP/DM operate in 2.4A mode;
6	DP	O/I	DP date line to connector, output for hand-shake voltage to portable equipment, high impedance while disabled
7	DM	O/I	DM data line to connector, input for hand-shake voltage from portable equipment high impedance while disabled
8	OUT	0	Power-switch output, connected to VBUS of USB; connect a 22µF or greater ceramic capacitor from OUT to GND as close to the IC as possible

⁽¹⁾ G = Ground, I = Input, O = Output, P = Power

ABSOLUTE MAXIMUM RATINGS (1)

Over recommended operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT		
Supply Voltage Range	IN	-0.3	7.0	V	
Input voltage range	DP,DM	-0.3	5.8		
Continuous output sink current	DP input current, DM input current		35	A	
Continuous output source current	DP output current, DM output current		35	mA	
ESD rating, Human Body	IN		2	kV	
Model (HBM)	DP, DM		2	KV	
Operating Junction Temperature	TJ	-40	125	°C	
Storage Temperature Range	T _{stg}	-65	150	30	

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

	THERMAL METRIC		
θ_{JA}	EMSOP8 Package thermal impedance ⁽¹⁾	65	°C/W

⁽¹⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

	PARAMETER	MIN	MAX	UNIT
V _{IN}	Input voltage of IN	4.5	6.5	V
V _{DP/DM}	DP data line input voltage		5.5	V
I _{DP/DM}	Continuous sink/source current		±10	mA
R _{SET}	Resistance of R _{SET}	13	100	kΩ
lout	Continuous sink/source current	1000	4000	mA
T _J	Operating Junction Temperature	-40	125	°C

ELECTRICAL CHARACTERISTICS

Conditions are: TA = 25° C, VIN = SEL = 5.0 V, ENB = GND and RSET = 33.0k Ω . Positive current are into pins. All voltages are with respect to GND (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
Power Switch							
RDSON	EMSOP8 Package	I _{OUT} =1A		29	35	mΩ	
Tr	OUT voltage rise time			2.97	6.1		
Tf	OUT voltage fall time	C 4 F. D 400 O		0.70	1.5	ms	
Ton	OUT voltage turn-on time	CL = 1 μ F, RL = 100 Ω ,		4.35	8.5		
Toff	OUT voltage turn-off time			2.83	6.9	1	
Current Limit			·				
		Rset=14.7k	3.05	3.50	3.95		
los	OUT current limited	Rset=18.7k	2.40	2.75	3.10	A	
		Rset=33.0k	1.35	1.56	1.77		
Enable Pin (ENB)			•				
V _{ENB}	ENB threshold voltage, falling		0.7	1.33	2.0	V	
V _{ENB_HYS}	Hysteresis			150		mV	
R _{PD}	Pull Down Resistor			290	580	kΩ	
Hiccup Mode							
Vout_short	OUT Threshold Voltage to enter Hiccup mode			3.0		V	
Ton_HICCUP	ON Time of Hiccup mode			100		ms	
Toff_HICCUP	OFF Time of Hiccup mode		0.5	1.0	1.5	s	
Thermal Shutdown	Thermal Shutdown						
	Temperature Rising Threshold			160		°C	
	Hysteresis			20			

ELECTRICAL CHARACTERISTICS

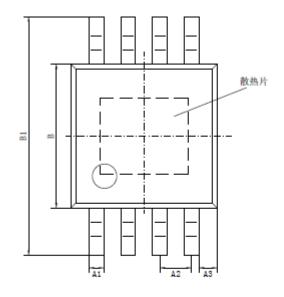
Conditions are: TA = 25° C, VIN = SEL = 5.0 V, ENB = GND and RSET = 19.1 k Ω . Positive current are into pins. All voltages are with respect to GND (unless otherwise noted).

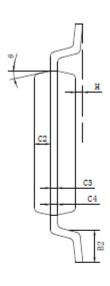
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
UNDERVOLTAGE L	UNDERVOLTAGE LOCKOUT						
Vuvlo	IN rising UVLO threshold voltage			2.40	2.65	V	
	Hysteresis			85		mV	
SUPPLY CURRENT			•				
lin	IN supply current	VIN=5.0V, ENB=0V		160	300		
I _{DDL}	IN Disable Supply Current	VIN=ENB=5.0V		0	5	μA	
BC 1.2 DCP MODE	(SHORT)		•				
RDPM_SHORT	DP / DM shorting resistance			125	200	Ω	
RDCHG_SHORT	Resistors connected DP /DM to GND after hand-shaking			200	400	kΩ	
VDPL_TH_DETACH	DP low threshold while detaching BC1.2 devices		310	330	350	mV	
VDPL_TH_DETACH_HYS	hysteresis			50		mV	
IPAD MODE 2.1A M	ode (SEL=1 or Floating)		·				
V _{DP_IPAD}	DP output voltage		2.5	2.7	2.9	V	
V _{DM_IPAD}	DM output voltage		1.85	2.0	2.15	V	
R _{DP_IPAD}	DP output impedance	I _{DP} = -5uA	20	30	40	kΩ	
R _{DM_IPAD}	DM output impedance	I _{DM} = -5uA	20	30	40	kΩ	
IPAD MODE 2.4A M	ode (SEL=0)						
V _{DP_IPAD}	DP output voltage		2.5	2.7	2.9	V	
V _{DM_IPAD}	DM output voltage		2.5	2.7	2.9	V	
RDP_IPAD	DP output impedance	I _{DP} = -5uA	20	30	40	kΩ	
R _{DM_IPAD}	DM output impedance	I _{DM} = -5uA	20	30	40	kΩ	
Galaxy Tab MODE							
V _{DP_GAL}	DP output voltage		1.1	1.2	1.3	V	
V _{DM_GAL}	DM output voltage		1.1	1.2	1.3	v	
R _{DP_GAL}	DP output impedance	I _{DP} = -5uA	70	105	140	1.0	
R _{DM_GAL}	DM output impedance	I _{DM} = -5uA	70	105	140	kΩ	

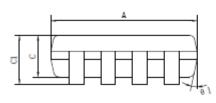


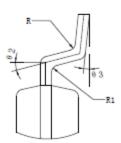
PACKAGE INFORMATION

EMSOP8









标注	最小(==)	最大(mm)	标注 尺寸	最小(==)	最大(==)		
A	2.90	3.10	C3	0.	152		
A1	0.28	0.35	C4	0.15	0.23		
A2	0.6	5TYP	H	0.02 0.15			
A3	0.3	75TYP	θ	12° TYP4			
В	2.90	3.10	θ 1	12° TYP4			
B1	4.70	5. 10	θ2	14	° TYP		
B2	0.45	0.75	03	0° ~ 6°			
С	0.75	0.95	R	0. 15TYP			
C1		1.10	R1	0. 15TYP			
C2	0.3	28TYP					
* 注: EMSO	P8产品框架基岛尺寸为	1.80X1.80, 散热片尺寸	为1.80X1.55	(单位: 22)	·		